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NihonHanda™
Nihon Handa Co.,Ltd. Head Office : 16F ARCA CENTRAL 2-1 Kinshi 1-Chome, Sumida-ku, Tokyo 130-0013, JAPAN Tel.+81-3-3624-5771 Fax.+81-3-3624-5775

Highly reliable Pb-free solder paste for SMT

Patent No. : 6370458

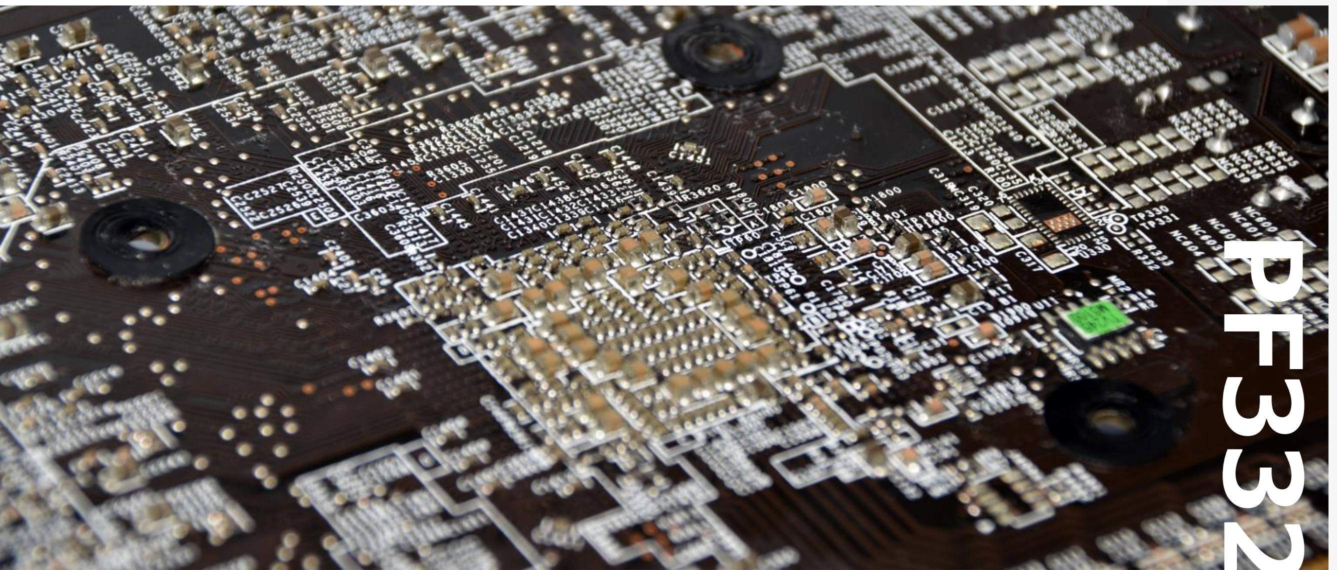
PF332C-150TO(A8)

Patented Pb-free solder alloy with high reliability

- Realized low void suitable for automotive application
- Adaptable same reflow profile with SAC305's
- Prevents occurrence of chip-side balls

Solder Paste for SMT

PF332C-150TO(A8)



General Characteristics

Item		Representative value	Test method
Alloy Composition		Sn-3.5Ag-0.7Cu-Bi-Sb-α	–
Solidus – Liquidus Temp.		211deg.C – 222deg.C	JIS Z 3198
Particle Size		20 to 38μm	–
Flux Content		11.5wt%	JIS Z 3197
Halide Content		0.03%	JIS Z 3197
Flux Type		ROL0	IPC J-STD-004
Copper Plate Corrosion Test		No corrosion	JIS Z 3197
Silver Chromate paper Test		No change	JIS Z 3197
Corrosion Test with Copper Mirror		No change to copper mirror	JIS Z 3197
Insulation Resistance Test	40℃90%RH after 168H	1.0×10^{11} Ω or more	JIS Z 3197
	85℃85%RH after 168H	5.0×10^{8} Ω or more	JIS Z 3197
Tack time at 100gf or more		24 hours	JIS Z 3284
Fluid Characteristics	Viscosity	200 Pa・s	JIS Z 3284
	Ti-value	0.55	JIS Z 3284

The above figures are representative values, not guaranteed specification. Available customization for alloy composition, particle size and flux content.
Please ask our sales staff for more details.

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Highly reliable Pb-free solder paste for SMT

PF332C-150TO(A8)

Patented Pb-free solder alloy with high reliability

Solder Paste for SMT PF332C-150TO(A8)

Highly suppressed void on back electrodes

Effective to back electrodes indispensable to prevent void occurrence

Cu-chip		Power transistor	
PF332C-150TO(A8)	Other product	PF332C-150TO(A8)	Other product
Void rate: 7.1%	Void rate: 18.6%	Void rate: 8.1%	Void rate: 14.5%

Void rate (Cu-chip): PF332C-150TO(A8) 7.1%, Other product 18.6% (axis 0%–30%)

Void rate (Power transistor): PF332C-150TO(A8) 8.1%, Other product 14.5% (axis 0%–30%)

<Test condition> Printed area : 5mm×5mm×0.12mm Substrate : Cu-plate Simulant part : Ni-plate（5mm×5mm×0.5mm）
Reflow condition : Preheat 150～190deg.C for 100sec., Peak temp. 240deg.C, 220deg.C or more for 30sec., Air reflow

Prevent occurrence of chip-side balls

Prevent to occur chip-side balls even at excessive soldering volume

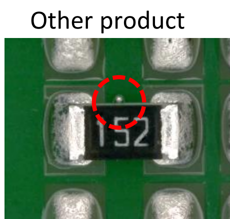
Just after printing

After reflow

PF332C-150TO(A8)

OK

Other product



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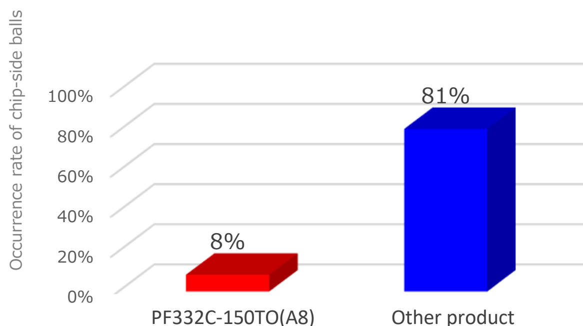
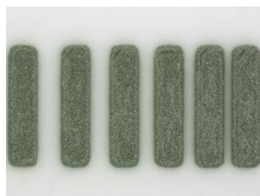
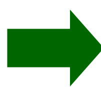


<Test condition>
Chip size : 3.2mm×1.6mm×0.6mm
Thickness of stencil : 0.2mm
Push length of chip : 0.2mm
Reflow condition : Preheat 150 to 190deg. C for 100sec.
Peak temp. 240℃ 220deg.C or more for 30sec., Air reflow

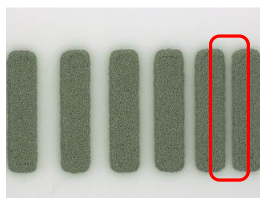
Prevent to occur heat slump

Just after printing

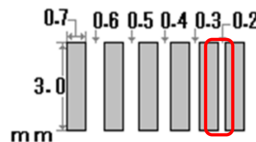




After reflow



No bridge between 0.2mm



【Test method】: JIS Z 3284
Printing pattern : Above drawing, t=0.2mm
Substrate : Ceramic plate（50mm×50mm×0.8mm）
Heating condition : 150deg.C w/ air circulation oven